AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-5. (Cancelled)

6. (Currently Amended) A pseudo wafer comprising a plurality of semiconductor chips each having at least their electrodes formed solely on one surface thereof, wherein interspaces between each individual one of said chips and bottom surfaces thereof are continuously covered with said protective material, and the chips are bonded with each other via the protective material ~~and further wherein the protective material adjacent the side surfaces of each semiconductor chip is cut to provide substantially vertical side walls of protective material formed adjacent the sides of the semiconductor chips~~, there being substantially none of the protective material formed on the one surface at which the electrodes are formed, the electrodes being covered with a solder material for forming a solder ball.

7. (Original) The pseudo wafer according to claim 6 wherein said protective material comprises either one of an organic insulating resin and an inorganic insulating material.

8. (Previously Presented) The pseudo wafer according to claim 6 wherein said plurality of semiconductor chips arrayed thereon are diced at a position of said protective

material between said plurality of semiconductor chips and thereafter mounted on a packaging substrate such that the protective material adjacent the side surfaces of the semiconductor chip is cut to provide substantially vertical side walls of protective material formed adjacent the sides of the semiconductor chip.

9. (Original) The pseudo wafer according to claim 8 wherein a solder bump is formed on said electrode.